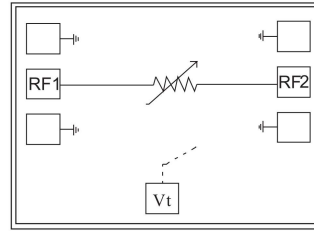


Performance

- Frequency: 2~3GHz
- Insertion loss: 1.5dB
- Max. Attenuation: 40dB
- Chip size: 1.5*1.4*0.1mm

Function Diagram

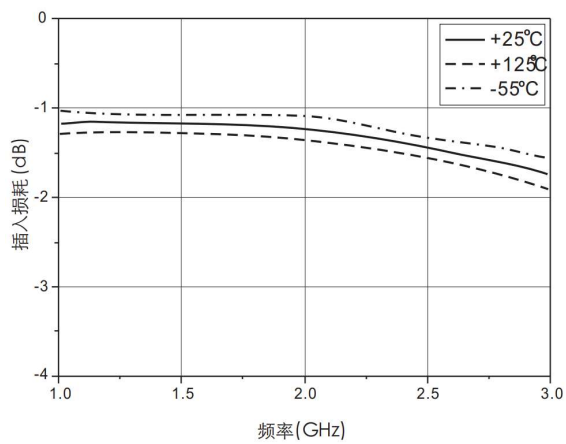


Electrical Specifications (Ta=+25°C, 50Ω system)

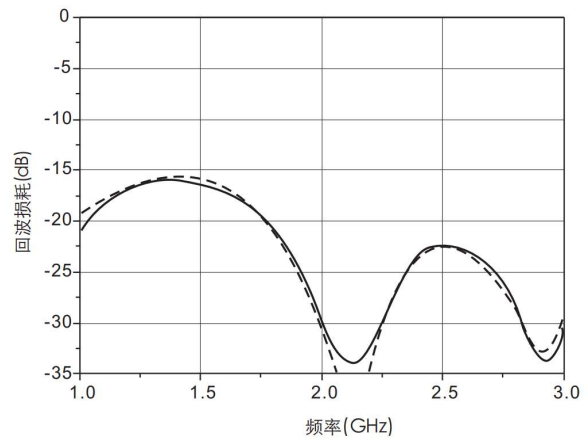
Parameter	Min	Typical	Max	Unit
Frequency Range		2~3		GHz
Insertion Loss	-	1.5	-	dB
Attenuation	0	-	40	dB
Input/Output return loss	-	-15	-	dB
Attenuation Flatness	-	±1	-	dB

Test Curves (Die chip + Bonding line test)

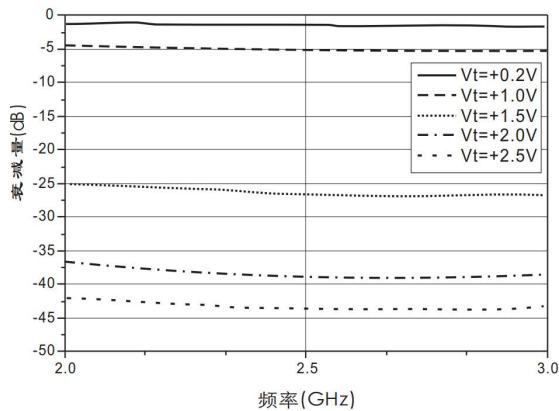
Insertion Loss vs. Freq



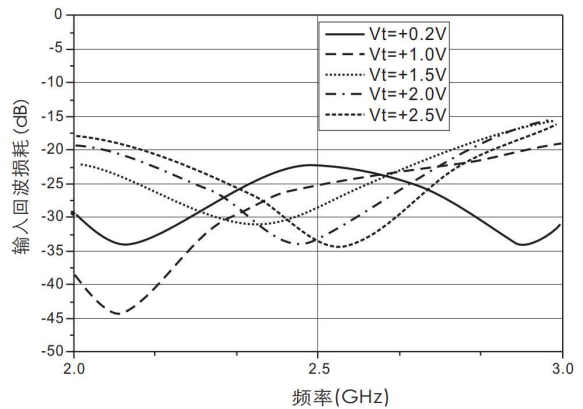
Input/Output Return loss (Ref) vs. Freq



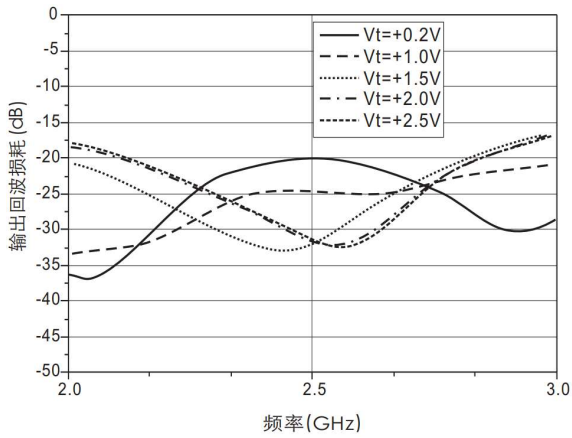
Attenuation vs. Freq



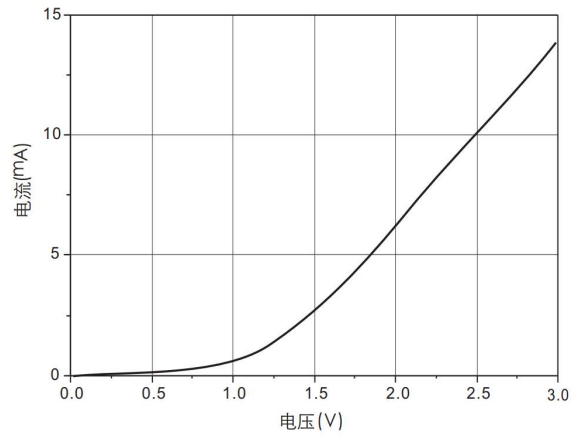
Attenuation state Input Return loss vs. Freq



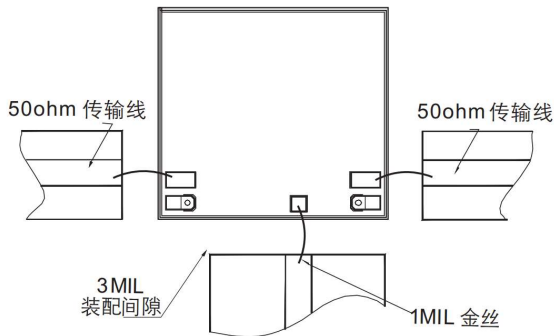
Attenuation state Output Return loss vs. Freq



Current vs. Control Voltage



Application



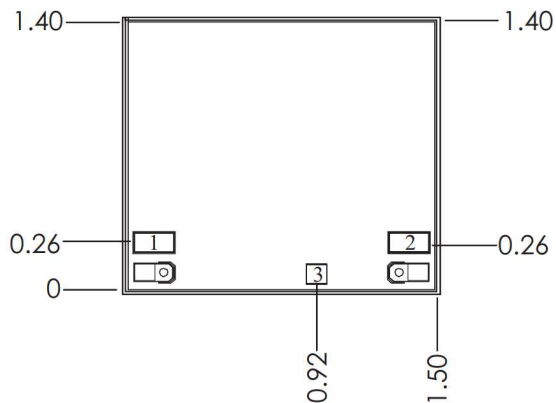
Absolute Rating

RF Input Power	+25dBm
Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C
Static Protection (HBM)	Class 1A



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Size



Note:

- Unit: μm
- Bottom side is gold plated
- Bottom side is GND
- Bonding pads are gold plated, Pad size: 200*100(μm), 100*100(μm)
- Don't bond on thru holes
- Tolerance: $\pm 50\mu\text{m}$

Bonding Pads Definition

Number	Symbol	Description
1、2	RF1、RF2	RF ports, 50ohm
3	Vt	Control port